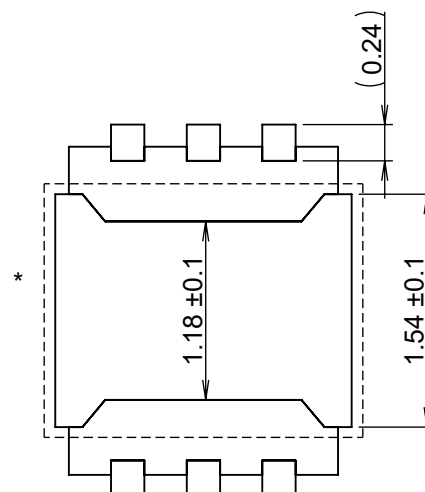
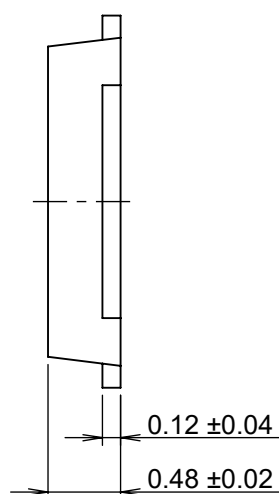
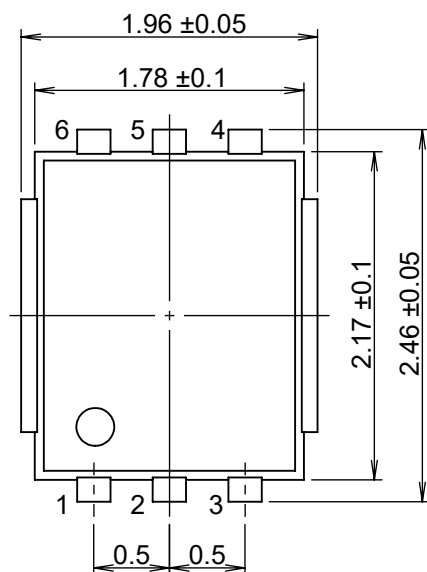
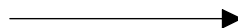
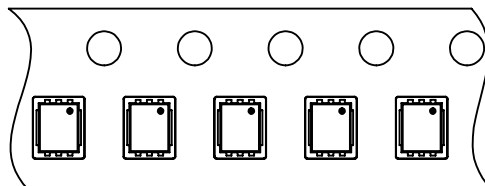
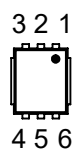
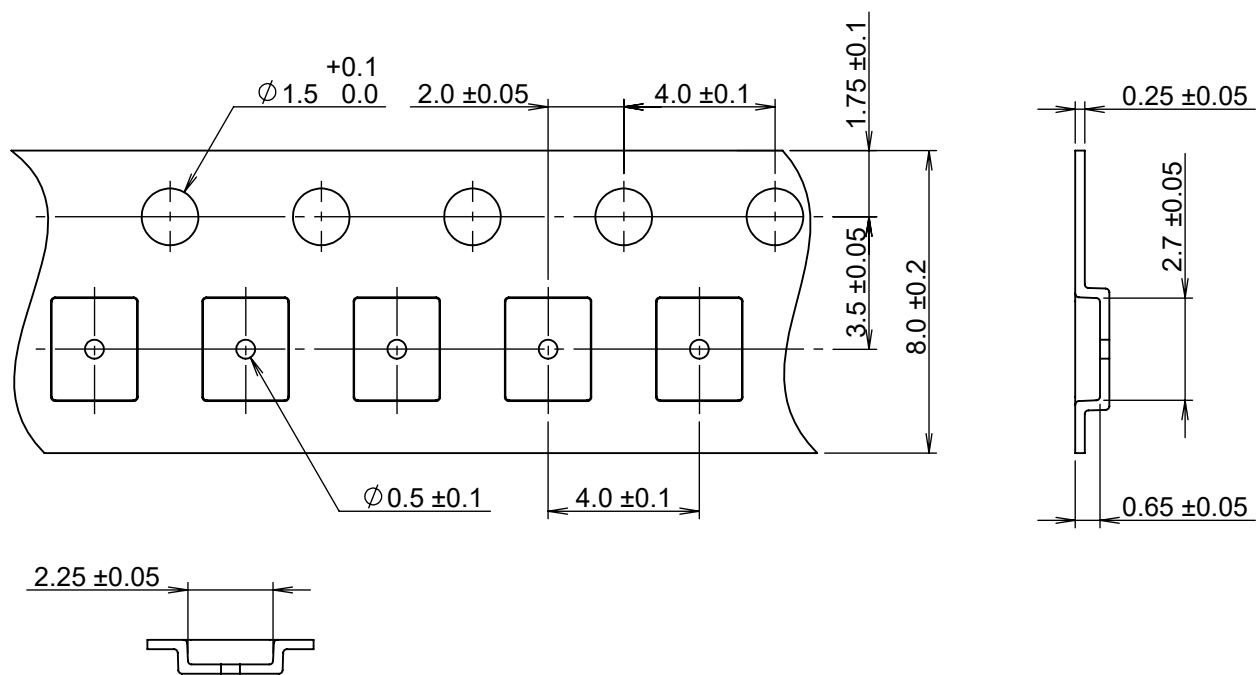


* The heat sink of back side has different electric potential depending on the product.
Confirm specifications of each product.
Do not use it as the function of electrode.

No. PJ006-B-P-SD-1.0

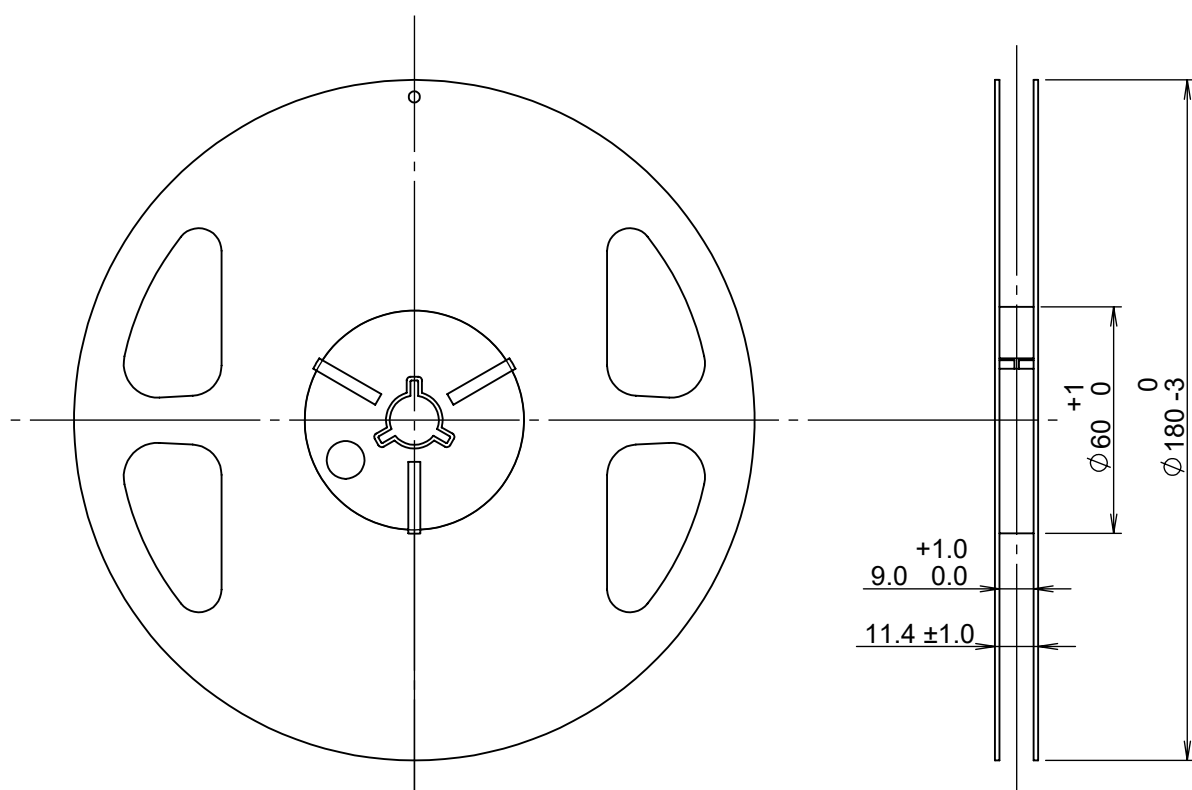
TITLE	HSNT-6-C-PKG Dimensions
No.	PJ006-B-P-SD-1.0
ANGLE	
UNIT	mm
ABLIC Inc.	



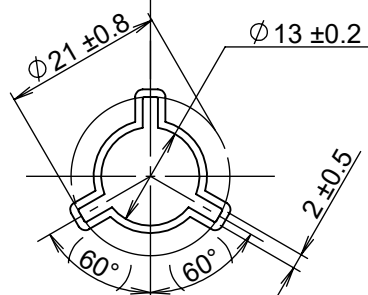
Feed direction

No. PJ006-B-C-SD-1.0

TITLE	HSNT-6-C-Carrier Tape
No.	PJ006-B-C-SD-1.0
ANGLE	
UNIT	mm
ABLIC Inc.	

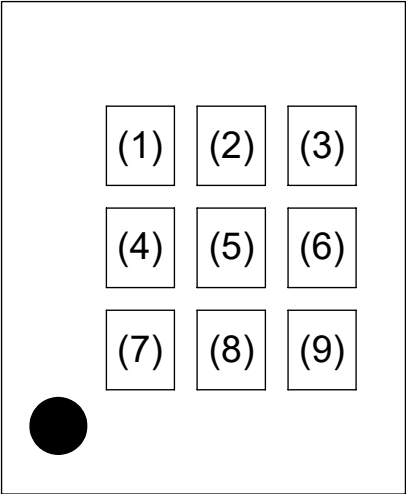


Enlarged drawing in the central part



No. PJ006-B-R-SD-1.0

TITLE	HSNT-6-C-Reel		
No.	PJ006-B-R-SD-1.0		
ANGLE		QTY.	5,000
UNIT	mm		
ABLIC Inc.			



PKG PIN#1

(1) to (4) : Product code

(5) : Year of assembly

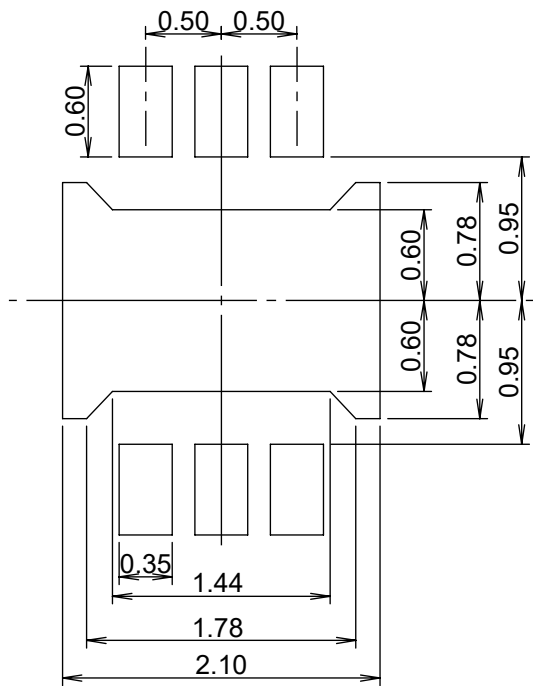
(6) : Month of assembly

(7) to (9) : Lot No.

No. PJ006-B-M-SD-1.0

TITLE	HSNT-6-C-Markings		
No.	PJ006-B-M-SD-1.0		
ANGLE		TYPE	LASER
UNIT			
ABLIC Inc.			

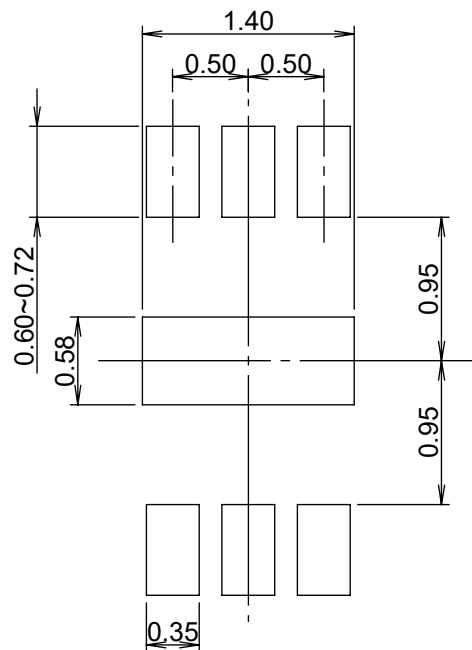
Land Recommendation



Caution It is recommended to solder the heat sink to a board in order to ensure the heat radiation.

注意 放熱性を確保する為に、PKGの裏面放熱板 (ヒートシンク) を基板に半田付けすることを推奨いたします。

Stencil Opening



No. PJ006-B-LM-SD-1.0

- Caution
- ① Mask aperture ratio of the lead mounting part is 100%~120%.
 - ② Mask aperture ratio of the heat sink mounting part is 30%.
 - ③ Mask thickness: t0.12mm
 - ④ Reflow atmosphere: Nitrogen atmosphere is recommended.
(Oxygen concentration: 1000ppm or less)

- 注意
- ① リード実装部のマスク開口率は100%~120%です。
 - ② 放熱板実装のマスク開口率は30%です。
 - ③ マスク厚み: t0.12mm
 - ④ リフロー雰囲気・窒素雰囲気
(酸素濃度1000ppm以下) 推奨

TITLE	HSNT-6-C -Land & Stencil Opening
No.	PJ006-B-LM-SD-1.0
ANGLE	
UNIT	mm
ABLIC Inc.	